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Sheet 1 of 1

<b>INFORMATION DISCLOSURE STATEMENT</b> 	Atty Docket:	00AG11453325
	Serial No.:	10/036,335
	Applicant:	MAGNI ET AL.
	Filing Date:	December 26, 2001
	Group:	

**U.S. PATENT DOCUMENTS**


Examiner Initials		Document Number	Date	Name	Class	Sub Class	Filing Date
<i>AD</i>	AA	5,275,547	01/4/94	Brown	425	129.1	01/3/92
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						

**FOREIGN PATENT DOCUMENTS**

		Document Number	Date	Country	Class	Sub Class	Translation.
<i>AD</i>	AM	0 813 236	12/17/97	EP	<del>H04L</del>	<del>2113</del>	
<i>AD</i>	AN	87/04973	08/27/87	WO	<del>B00C</del>	<del>45/26</del>	
	AO						
	AP						

**OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)**

<i>AD</i>	AQ	Patent abstracts of Japan, Vol. 1998, No. 08 dated June 30, 1998; publication No. 10075040 published on March 17, 1998, entitled "Method for Manufacturing Resin-Coated Circuit Board"; Applicant: Toshiba Chem Corp.
	AR	

<b>EXAMINER:</b> 	<b>DATE CONSIDERED:</b> 2/2004
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.